Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4	((first adj dummy) and (second adj dummy) and metal and (anneal\$6 or heat\$6 or (thermal adj treat\$8))).clm.	US-PGPUB	OR	ON	2005/08/19 10:20
L5	748	(438/296).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 10:28
L6	11	438/296.ccls. and (dummy adj (gate or electrode)) and ((thermal adj treat\$6) or anneal\$5 or heat\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 10:47
L7 _.	15	438/296.ccls. and (dummy adj (gate or electrode))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 10:30
L9	0	7 and (metal adj (film or layer)) and (thermal adj treat\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 10:34
L11	70	438/183,296.ccls. and (dummy adj (gate or electrode)) and ((thermal adj treat\$6) or anneal\$5 or heat\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 10:50
L13	1858	(438/270).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 10:50
L14	151	(438/183).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 10:55

115	124	(420/10E) CCLC	LIC DCDLID		055	2005/00/10 10:55
L15	124	(438/195).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 10:55
L16	212	(438/663):CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 11:09
L17	971	(438/275).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 11:09
S1	195	438/926	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 10:46
S2	147	(first adj dummy) and (second adj dummy) and metal and (anneal\$6 or heat\$6 or (thermal adj treat\$8))	US-PGPUB; USPAT	OR	ON	2005/08/11 17:29
S3	97	(first adj dummy) and (second adj dummy) and metal and (anneal\$6 or heat\$6 or (thermal adj treat\$8)) and @ad<="20030114"	US-PGPUB; USPAT	OR	ON	2005/08/19 10:19
S4	1054	(first adj dummy) and (second adj dummy)	US-PGPUB; USPAT	OR	ON	2005/08/19 10:19
S5	423	S4 and metal	US-PGPUB; USPAT	OR	ON	2005/08/11 17:30
S6	152	S5 and (anneal\$6 or heat\$6 or (thermal adj treat\$8))	US-PGPUB; USPAT	OR	ON	2005/08/11 17:30
S7	97	S6 and @ad<="20030114"	US-PGPUB; USPAT	OR	ON	2005/08/11 17:30
S8	0	S7 and (first adj temperature)	US-PGPUB; USPAT	OR	ON	2005/08/11 17:31
S9	97	S7 and (first)	US-PGPUB; USPAT	OR	ON	2005/08/11 17:31
S10	97	S9 and second	US-PGPUB; USPAT	OR	ON	2005/08/11 17:34

S11	747	(438/296).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/11 17:33
S12	3	(("20040262601") or ("20040002176") or ("6429450")). PN:	US-PGPUB; USPAT	OR	OFF	2005/08/19 10:24
S13	1054	(first adj dummy) and (second adj dummy)	US-PGPUB; USPAT	OR	ON	2005/08/15 15:48
S14	423	S13 and metal	US-PGPUB; USPAT	OR	ON	2005/08/15 15:48
S15	152	S14 and (anneal\$6 or heat\$6 or (thermal adj treat\$8))	US-PGPUB; USPAT	OR	ON	2005/08/15 15:48
S16	97	S15 and @ad<="20030114"	US-PGPUB; USPAT	OR	ON	2005/08/15 15:48
S17	97	S16 and (first)	US-PGPUB; USPAT	OR	ON	2005/08/15 15:48
S18	97	S17 and second	US-PGPUB; USPAT	OR	ON	2005/08/15 15:48
S19	77	S18 and semiconductor	US-PGPUB; USPAT	OR	ON	2005/08/15 15:51
S20	2	("20040142546").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/15 18:00
S21		("4840923" "4933743" "4987101" "5034799" "5103288" "5148260" "5324683").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/15 17:55
S22	1302	kudo.in. and hiroshi	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/15 18:02
S23	117	S22 and fujitsu	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/15 18:01

S24	5	S23 and dummy	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/15 18:01
S25	7	S22 and dummy	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/15 18:03
S26	5	naganuma.in. and junko	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/15 18:03
S27	88	kishii.in. and sadahiro	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/15 18:03
S28	4	S27 and dummy	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/08/15 18:03